

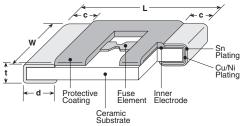


thin film chip fuse

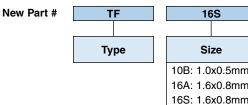


dimensions

and construction



ordering information



features

- ROHS
- Small, lightweight design
- Special manufacturing method stabilizing fusing characteristics and occupying less area
- Low power consumption and less voltage drop due to low internal resistance
- Suitable for overcurrent protection of circuit block in electronic devices
- Suitable for flow and reflow soldering
- Marking: Black body color with white marking: TF10BN, TF10SN; white marking: TF10AT
- Products with lead-free terminations meet EU RoHS and China RoHS requirements

Туре	Dimensions inches (mm)					
(Inch Size Code)	L	W	С	d	t	
TF10BN (0402)	.04±.004 (1.0±0.1)	.02±.002 (0.5±0.05)	.008±.004 (0.2±0.1)	.01±.004 (0.25±0.1)	.015±.002 (0.4±0.05)	
TF16AT (0603)	.063±.004 (1.6±0.1)	.031±.003 (0.8±0.08)	.012±.004 (0.3±0.1)	.012±.004 (0.3±0.1)	.018±.002 (0.45±0.05)	
TF16SN (0603)	.063±.008 (1.6±0.2)	.031±.004 (0.8±0.1)	.012±.004 (0.3±0.1)	.012±.004 (0.3±0.1)	.015+ +.004 002 (0.4+ +0.1 -0.05)	

		N		
		_		
		Fus Charac	ing teristic	
mm		N: Norn	nal blow	
mm		T: Anti		
mm		(16A	only)	



Т			
Termi Mate	nation erial		
T:	Sn		

Packaging
TB: 2mm pitch punched paper (TF10BN only, 10,000 pieces/reel)
TD: 4mm pitch punched paper (TF16 only, 5,000 pieces/reel)

ΤE

applications and ratings

Part Designation	Marking	Rated Current	Fusing Time	Internal R. Maximum (mΩ)	Rated Voltage	Rated Ambient Temperature	Operating Temperature Range
TF10BN0.20	Α	0.20A		1990			
TF10BN0.25	С	0.25A		1270			
TF10BN0.315	D	0.315A		850			
TF10BN0.50	F	0.50A	Open within	320		+70°C	-55°C to +125°C
TF10BN0.63		0.63A	5 sec. at 200%	200			
TF10BN0.80	K	0.80A	rated current	135	24V		
TF10BN1.00	L	1.00A	(Refer to Fusing	115			
TF10BN1.25	M	1.25A	Characteristics	90			
TF10BN1.60	N	1.60A	graph)	58			
TF10BN2.00	S	2.00A		42			
TF10BN2.50	T	2.50A		35			
TF10BN3.00	V	3.00A		30			
TF16AT0.25	С	0.25A		498			
TF16AT0.315	D	0.315A		384	1		
TF16AT0.50	F	0.50A	Open within 5 sec. at 200%	198	32V	+70°C	-55°C to +125°C
TF16AT0.63		0.63A		143			
TF16AT0.80	K	0.80A	rated current	120			
TF16AT1.00	L	1.00A	(Refer to Fusing	94			
TF16AT1.25	M	1.25A	Characteristics	73			T125 C
TF16AT1.60	N	1.60A	graph)	59			
TF16AT2.00	S	2.00A		42			
TF16AT2.50	T	2.50A		32			

For further information on packaging, please refer to Appendix A.

Specifications given herein may be changed at any time without prior notice. Please confirm technical specifications before you order and/or use.





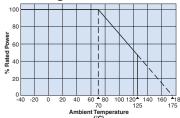
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applications and ratings (continued)

Part Designation	Marking	Rated Current	Fusing Time	Internal R. Maximum (mΩ)	Rated Voltage	Rated Ambient Temperature	Operating Temperature Range
TF16AT3.15	U	3.15A	Open within 5 sec. at	24			-55°C
TF16AT4.00	X	4.00A	200% rated current (Refer to Fusing	17	32V	+70°C	to
TF16AT5.00	Υ	5.00A	Characteristics graph)	14			+125°C
TF16SN0.20	Α	0.20A		1500			
TF16SN0.25	С	0.25A		960			
TF16SN0.315	D	0.315A		600			
TF16SN0.40	Н	0.40A	Open within	440			
TF16SN0.50	F	0.50A	1 sec. at 200%	300			
TF16SN0.63	1	0.63A	rated current	190			-40°C
TF16SN0.70	J	0.70A	(Refer to Fusing	170	32V	+70°C	to
TF16SN0.80	K	0.80A	Characteristics	135			+125°C
TF16SN1.00	L	1.00A		103			
TF16SN1.25	М	1.25A	graph)	78			
TF16SN1.60	N	1.60A		58			
TF16SN2.00	S	2.00A		47			
TF16SN2.50	T	2.50A		38			
TF16SN3.15	U	3.15A		28			

environmental applications

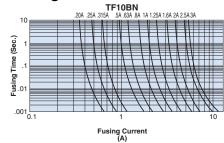
Derating Curve

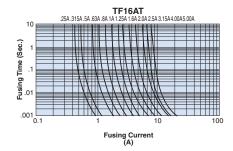


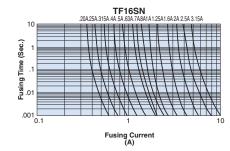
Stationary Current: Regard the peak of stationary current waveform as stationary current value when the stationary current is repeated pulse.

Temperature Derating: Rated current needs to be derated if used at an ambient temperature 70°C or above. Refer to the derating coefficient on the left figure.

Fusing Characteristics







Performance Characteristics

	Require	ement	
Parameter	Limit	Typical	Test Method
Clearing Time	Within 1 second (16AT, SN) Within 5 seconds (10BN)	_	200% of rated voltage shall be carried
Bending Test	No mechanical damages	_	Distance between holding points: 90mm, Bending: 3mm, 1 time (BN, AT), 2mm, 1 time (SN)
Resistance to Solder Heat	±10%	±4.5% (16SN) ±5% (10BN, 16AT)	260°C ± 5°C, 10 seconds ± 0.5 ⁻⁹ second
Solderability	95% coverage minimum	_	230°C ± 5°C, 3 seconds ± 0.5 second
Load Life	±10%	±4.5%(16SN) ±5% (10BN, 16AT)	70°C ± 2°C, 1000 hours, rated current x 100%, 1.5 hr ON, 0.5 hr OFF cycle
Load Life Moisture	±10%	±3% (10BN) ±4.5% (16SN), 5% (16AT)	40°C ± 2°C, 90 - 95% RH, 1000 hours, rated current x 100% (10BN, 16SN), x 75% (16AT), 1.5 hr ON, 0.5 hr OFF cycle
Rapid Change of Temperature	±10%	±4% (16SN) ±5% (10BN, 16AT)	16SN: -40°C ± 2°C (30 minutes), 10BN, 16AT: -55°C ± 2°C, +125°C (30 minutes), 10 cycles
Resistance to Solvent	No evidence of damages to protective coating and marking	_	Conforming to MIL-STD-202F
Residual Resistance	10kΩ and more	_	Measure DC resistance after fusing

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1/06/14